

Title (en)

HIGH-IMPACT POLYSTYRENE RESIN COMPOSITION

Title (de)

SCHLAGFESTE POLYSTYROLHARZZUSAMMENSETZUNG

Title (fr)

COMPOSITION DE RESINE DE POLYSTYRENE EXTREMEMENT RESISTANTE AUX CHOCS

Publication

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Application

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Priority

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Abstract (en)

[origin: EP0733675A1] The present invention relates to an impact resistant polystyrene composition which comprises 5 to 97% by weight of an (a) styrenic polymer having syndiotactic configuration, 2 to 95% by weight of a (b) rubbery elastomer having an olefinic component or a polyolefin, and 0.5 to 10% by weight of a (c) styrene/olefin block or graft copolymer having a micro-phase separation temperature of 180 DEG C at the highest when diluted with dioctyl phthalate to a solution with a concentration of 60% by weight. According to the present invention, an impact resistant polystyrene composition can be provided which is greatly enhanced in impact resistance and extensibility without impairing heat resistance and modulus of elasticity.

IPC 1-7

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Citation (search report)

- [X] EP 0318793 A1 19890607 - IDEMITSU KOSAN CO [JP]
- [X] EP 0324398 A1 19890719 - IDEMITSU KOSAN CO [JP]
- See references of WO 9611233A1

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